

# MS75N75

### 75V N-Channel MOSFET

Features

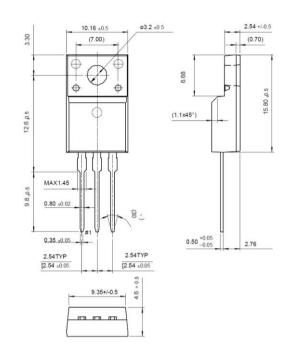
- RDS(on) (Max 0.017 Ω )@VGS=10V
- Gate Charge (Typical 85nC)
- Improved dv/dt Capability, High Ruggedness
- 100% Avalanche Tested
- Maximum Junction Temperature Range (175°C)
- RoHS compliant package

Package type : TO-220AB

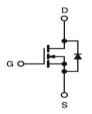
Packing & Order Information

50/Tube ; 1,000/Box





Graphic symbol



#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (Tc=25°C unless otherwise specified)						
Symbol	Parameter	Value	Unit			
V <sub>DSS</sub>	Drain-Source Voltage	75	V			
Ір	Drain Current -Continuous (TC=25°C)	75	Α			
1D	Drain Current -Continuous (TC=100°C)	52.5	А			
I <sub>DM</sub>	Drain Current –Pulsed	300	А			
V <sub>GS</sub>	Gate-Source Voltage	±20	V			
E <sub>AS</sub>	Single Pulsed Avalanche Energy	1350	mJ			
E <sub>AR</sub>	Repetitive Avalanche Energy	9	mJ			
dv/dt	Peak Diode Recovery dv/dt	7.0	V/ns			
		190	W			
PD	Power Dissipation (TC= $25^{\circ}$ C) - Derate above $25^{\circ}$ C	1.27	W/°C			
$T_J/T_{STG}$	Operating and Storage Temperature Range	-55 to +150	°C			
т	Maximum lead temperature for soldering purposes,	200	°C			
$T_L$	1/8" from case for 5 seconds	300	°C			

•Drain current limited by maximum junction temperature



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Thermal Resistance Characteristics							
Symbol	Parameter	Typ.	Max.	Units			
R <sub>0JC</sub>	Junction-to-Case		1.43	°C/W			
$R_{\theta JA}$	Junction-to-Ambient		62.5	C/w			

On Characteristics							
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units	
V <sub>GS</sub>	Gate Threshold Voltage	$V_{\rm DS}=V_{\rm GS}, I_{\rm D}=250\mu A$	2.0		4.0	V	
RDS(ON)	Static Drain-Source On-Resistance	$V_{GS} = 10 V, I_D = 3.75 A$		14	17	mΩ	

Off Characteristics							
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}=0~V$ , $I_{D}\!=\!250\mu A$	75			v	
$\Delta BV_{DSS}$	Breakdown Voltage Temperature Coefficient	${\rm I}_{\rm D}{=}250\mu A,$ Referenced to $25^{\circ}{\rm C}$		0.08		V/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 75 \ V \ , \ V_{GS} = 0 \ V \ V_{DS} = 60 \ V \ , \ V_C = 125^\circ C \label{eq:VDS}$			10 100	μA	
I <sub>GSSF</sub>	Gate-Body Leakage Current,Forward	$V_{GS} = 20 \ V \mbox{, } V_{DS} = 0 \ V$			100	μA	
Igssr	Gate-Body Leakage Current,Reverse	$V_{GS} = -20 \ V \ , \ V_{DS} = 0 \ V$			-100	nA	

Dynamic Characteristics								
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units		
CISS	Input Capacitance	$V_{DS} = 25 V, V_{GS} = 0 V,$ f = 1.0MHz		3000		pF		
Coss	Coss Output Capacitance			1100		pF		
C <sub>RSS</sub>	Crss Reverse Transfer Capacitance			250		pF		

Switching Characteristics								
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units		
td(on)	Turn-On Time	$V_{DS} = 37.5 \text{ V}, \text{ I}_D = 75 \text{ A},$ $R_G = 25 \Omega$		25	60	ns		
tr	Turn-On Rise Time			300	700	ns		
t <sub>d(off)</sub>	Turn-Off Delay Time			150	310	ns		
tf	Turn-Off Fall Time			180	370	ns		
Qg	Total Gate Charge			85	110	nC		
Qgs	Gate-Source Charge	$V_{DS} = 60 \text{ V}, I_D = 10 \text{ A},$ - V_{GS} = 75 V		15		nC		
$Q_{gd}$	Gate-Drain Charge			40		nC		



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Source-Drain Diode Maximum Ratings and Characteristics								
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units		
Is	Continuous Source-Drain Diode Forwa	rd Current			75			
I <sub>SM</sub>	ISM Pulsed Source-Drain Diode Forward Current				300	A		
V <sub>SD</sub>	Source-Drain Diode Forward Voltage	$I_S=75\ A\ ,\ V_{GS}=0\ V$			1.5	V		
t <sub>rr</sub>	Reverse Recovery Time	$I_S = 75 \text{ A}, V_{GS} = 0 \text{ V}$		90		ns		
Q <sub>rr</sub>	Reverse Recovery Charge	diF/dt=100A/µs		250		μC		

Notes:

1. Repeativity rating : pulse width limited by junction temperature

2. L = 0.32mH, I\_{AS} =75A,  $V_{DD}$  = 25V,  $R_{G}$  = 25 $\Omega$  , Starting TJ = 25°C

3. I<sub>SD</sub>  $\leq$  75A, di/dt  $\leq$  300A/us, VDD  $\leq$  BVDSS, Starting TJ = 25°C

4. Pulse Test : Pulse Width  $\leq$  300us, Duty Cycle  $\leq$  2%

5. Essentially independent of operating temperature.



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